

tb_frame_A3_J_ME_S
Rev. E 2006/04/15

注記
NOTES:

1. 材質

MATERIAL

ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)

2. メッキ仕様

PLATING

ターミナル

TERMINAL

接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM

ネイル

NAIL

錫メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM

3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた

平坦度は、0.1ミリメートル以下。

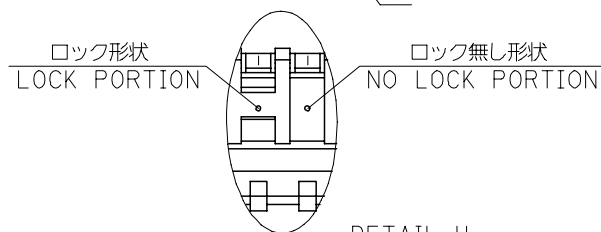
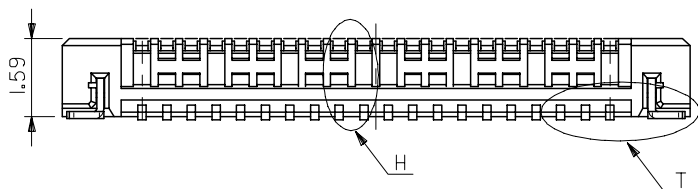
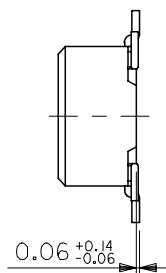
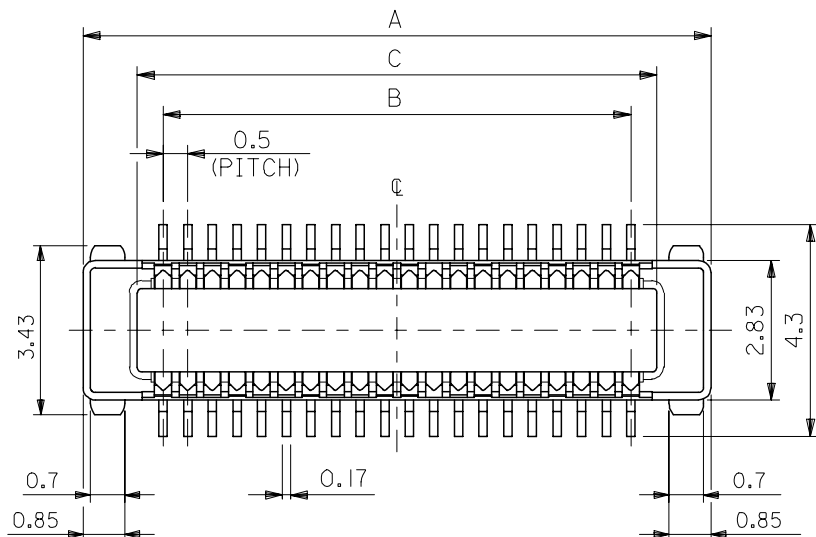
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS
COPLANARITY TO BE 0.1 MAXIMUM.

4. 嵌合相手: 54363-****

MATED CONN.: 54363-****

5. 本製品は55650-****1の鉛フリー品である。

THIS PRODUCT IS LEAD FREE OF 55650-****1

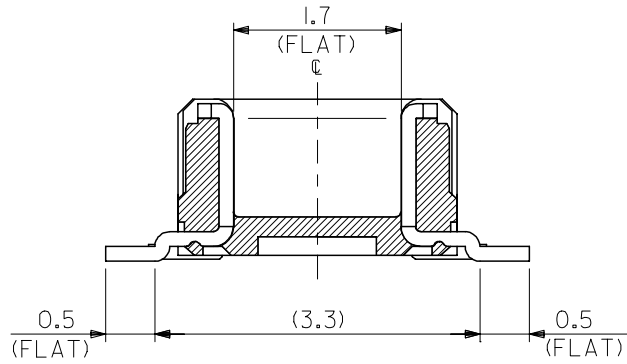


DETAIL H
SCALE 2:1

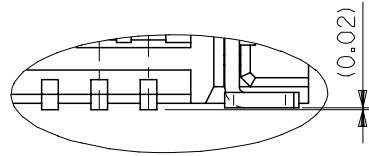
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4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-****1

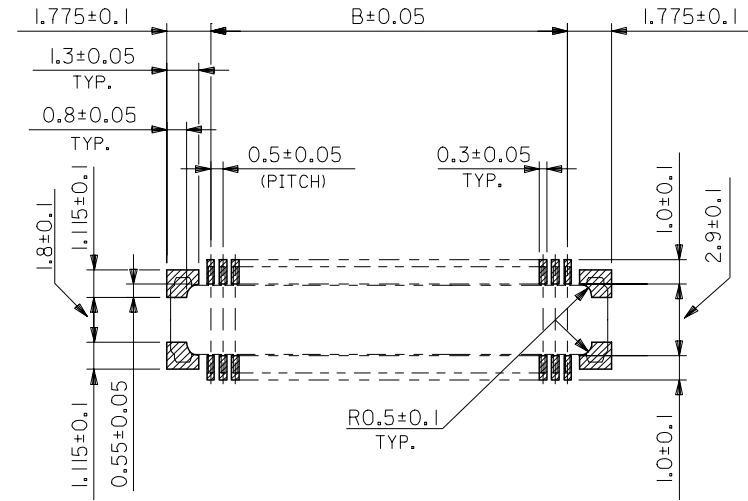
REVISED	EC NO.: J2008-0540 DRAWN: YAOYAGI CHKD: KOTOYODA APPR: NUKIITA	2007/09/03 2007/09/03 2007/09/04	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-			
				10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09				
				30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09				
				ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-55650-013			1 OF 2
						MOLEX INCORPORATED					
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
T部詳細



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)

REVISED EC NO.: J2008-0540 DRAWN-YAOYAGI CHKD-KTOYODA APPR:NIKI TA	2007/09/03 2007/09/04 2007/09/04	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
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			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.			SHEET NO.
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-55650-013			2 OF 2
			REV	B	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				